

**Search strategies for Case No. 10085716.  
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Ex. Andre' Stevenson**

USPT,PGPB,DWPI  
(6173750 ) and (test\$2 or testing)

USPT,PGPB,DWPI  
(6173750 ) and (visual\$2 or image\$2)

USPT,PGPB,DWPI  
(6173750 ) and tape\$2 and reel\$4

USPT,PGPB,DWPI  
6173750

USPT,PGPB,DWPI  
(((6173750 ) and (saw\$3 or dice\$2)) ) and  
(mark\$2 or marking) ) and tape\$2 and reel\$4

USPT,PGPB,DWPI  
(((6173750 ) and (saw\$3 or dice\$2)) ) and  
(mark\$2 or marking)

USPT,PGPB,DWPI  
(6173750 ) and (saw\$3 or dice\$2)

USPT,PGPB,DWPI  
(6173750 ) and (saw or dice)

USPT,PGPB,DWPI  
(((6173750 ) (die near (strip\$2 or tape\$2)) )  
and (mold\$3 or molding or fitting or conforming  
or conform\$2) near die\$2) ) and plasma\$2 ) and  
(clean or cleaning)

USPT,PGPB,DWPI  
(((6173750 ) (die near (strip\$2 or tape\$2)) ) and  
(mold\$3 or molding or fitting or conforming or  
conform\$2) near die\$2) ) and plasma\$2

USPT,PGPB,DWPI  
(6173750 ) and (tape\$3 or reel\$3)

USPT,PGPB,DWPI  
6173750

USPT,PGPB,DWPI  
((6173750 )and (mark\$2 or marking\$2) ) and  
(tape\$2 or reel\$2) and (visual\$2 or image\$3)

USPT,PGPB,DWPI  
(6173750 ) and (mark\$2 or marking\$2)

USPT,PGPB,DWPI

((die near (strip\$2 or tape\$2) )and (mold\$3 or  
molding or fitting or conforming or conform\$2)  
near die\$2 ) and ball near (attach\$2 or  
attachment\$2)

USPT,PGPB,DWPI

(((die near (strip\$2 or tape\$2) )and  
cleaning near die\$2 ) and plasma\$3) ) and die  
near (strip\$2 or tape\$2) and cleaning near die\$2  
and plasma\$3

USPT,PGPB,DWPI

(6173750 ) and (mold\$3 or molding or fitting  
or conforming or conform\$2) near die\$2

USPT,PGPB,DWPI

(6173750 ) (die near (strip\$2 or tape\$2) ) and  
(mold\$3 or molding or fitting or conforming or  
conform\$2) near die\$2

USPT,PGPB,DWPI  
6173750

USPT,PGPB,DWPI

(die near (strip\$2 or tape\$2) ) and (mold\$3 or  
molding or fitting or conforming or conform\$2)  
near die\$2

USPT,PGPB,DWPI

((die near (strip\$2 or tape\$2) )and cleaning  
near die\$2 ) and plasma\$3

USPT,PGPB,DWPI

(die near (strip\$2 or tape\$2) ) and cleaning  
near die\$2

USPT,PGPB,DWPI

die near (strip\$2 or tape\$2)

USPT,PGPB,DWPI

die near (strip\$2 or tape\$2) and (cure\$2 or  
curing\$2 or cleaning) and (bond\$2 or bonding or  
attach\$2 or attaching) near (tape\$2 or strip\$2)  
and plasma\$3

USPT

die near (strip\$2 or tape\$2) and (cure\$2 or  
curing\$2 or cleaning) and (bond\$2 or bonding or  
attach\$2 or attaching) near (tape\$2 or strip\$2)  
and plasma\$3

USPT

((die near strip\$2) or die-strip\$2) and (cure\$2  
or curing\$2 or cleaning) and (bond\$2 or  
bonding) and plasma\$3

USPT

((((die near strip\$2) or die-strip\$2) and  
(test\$2 or testing\$2) )and (cure\$2 or curing\$2 or  
cleaning) )and (bond\$2 or bonding) ) and  
plasma\$3

6173750

USPT  
(((die near strip\$2) or die-strip\$2) and (test\$2 or testing\$2) )and (cure\$2 or curing\$2 or cleaning) ) and (bond\$2 or bonding)

USPT

((semiconductor\$2 or (integrated near circuit\$2)) and (rear or (back near end) or (back near side\$2) or (under near side\$2)) strip\$2) or die-strip\$2) ) and (test\$2 or testing\$2)

USPT  
(((die near strip\$2) or die-strip\$2) and (test\$2 or  
testing\$2) ) and (cure\$2 or curing\$2 or cleaning)

USPT

(semiconductor\$2 or (integrated near circuit\$2)) and (rear or (back near end) or (back near side\$2) or (under near side\$2)) and ((die near strip\$2) or die-strip\$2)

USPT ((die near strip\$2)  
or die-strip\$2) and (test\$2 or testing\$2)

USPT

(((6173750) )and (semiconductor\$2 or  
(integrated near circuit\$2)) and (rear or (back  
near end) or (back near side\$2) or  
(under near side\$2) and ((die near strip\$2) or  
die-strip\$2) and (test\$2 or testing\$2)) )and (rear  
or (back near end) or (back near side\$2) or  
(under near side\$2)) ) and ((die near strip\$2) or  
die-strip\$2) and (test\$2 or testing\$2)

((semiconductor\$2 or (integrated near circuit\$2)) and (rear or (back near end) or (back near side\$2) or (under near side\$2)) and (device\$2 or apparatus\$2) ) and (test\$2 or testing\$2) near ((die near strip\$2) or die-strip\$2 or diestrip\$2)

USPT

((((semiconductor\$2 or (integrated near circuit\$2)) and (rear or (back near end) or (back near side\$2) or (under near side\$2))) and (((die near strip\$2) or die-strip\$2) ) and (test\$2 or testing\$2) )and (semiconductor\$2 or (integrated near circuit\$2)) and (rear or (back near end) or (back near side\$2) or (under near side\$2) and (((die near strip\$2) or die-strip\$2) and (test\$2 or testing\$2) ) and (rear or (back near end) or (back near side\$2) or (under near side\$2) )

USPT

((semiconductor\$2 or (integrated near circuit\$2)) and (rear or (back near end) or (back near side\$2) or (under near side\$2)) and (device\$2 or apparatus\$2) ) and (test\$2 or testing\$2) near ((die near strip\$2) or die-strip\$2)

USPT

((6173750) ) and (semiconductor\$2 or  
(integrated near circuit\$2)) and (rear or (back  
near end) or (back near side\$2) or (under near  
side\$2) and ((die near strip\$2) or die-strip\$2) and  
(test\$2 or testing\$2))

USPTO  
(((semiconductor\$2 or (integrated near circuit\$2)) and (rear or (back near end) or (back near side\$2) or (under near side\$2)) and (device\$2 or apparatus\$2) )and ((die near strip\$2) or die-strip\$2) ) and (test\$2 or testing\$2)

ISPT

((6173750)) and (semiconductor\$2 or (integrated near circuit\$2)) and (rear or (back near end) or (back near side\$2) or side\$2) and ((die near strip\$2) or die-strip\$2) and (test\$2 or testing\$2))

JISDT

((semiconductor\$2 or (integrated near circuit\$2)) and (rear or (back near end) or (back near side\$2) or (under near side\$2)) and (device\$2 or apparatus\$2) ) and ((die near strip\$2) or die-strip\$2)

LISPT

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(semiconductor\$2 or (integrated near circuit\$2)) and (rear or (back near end) or (back near side\$2) or (under near side\$2)) and (device\$2 or apparatus\$2)